

L Number	Hits	Search Text	DB	Time stamp
4	4527	(29/739,742,743,762,412,417,833).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07
5	607	((29/739,742,743,762,412,417,833).CCLS.) and convey\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07
6	332	((29/739,742,743,762,412,417,833).CCLS.) and convey\$5) and electronic\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07
7	100	((29/739,742,743,762,412,417,833).CCLS.) and convey\$5) and electronic\$3) and cut\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07
8	640	((29/33k,33m,563,564,564.1,564.2,564.7).CCLS.) and convey\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07
9	41	((29/33k,33m,563,564,564.1,564.2,564.7).CCLS.) and convey\$5) and electronic) and (fasten\$4 or restrain\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07
10	323	(29/564.1).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07
11	54	((29/564.1).CCLS.) and electronic\$3) and (cutting or cutter or cut\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07
14	3823	(29/840,832).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07
15	0	20020148106.URPN.	USPAT	2004/02/21 16:07
16	0	"20013075630"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07
17	585	((29/840,832).CCLS.) and electronic and cut\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07
18	31416	H01L023/50.ipc.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07
19	72	(IC adj chip) near board and cutting	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07
20	215	IC near board and cutting	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07
21	11675	IC adj packages	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07

22	0	product adj accomodating adj device	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07
23	4250	(29/832,833,834,835,740,743).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07
24	2386	(29/33k,33m,563,564,564.1,564.2,564.7).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07
25	0	((29/33k,33m,563,564,564.1,564.2,564.7).CCLS.) or ((29/832,833,834,835,740,743).CCLS.) and cutters and electronic and (IC adj (chip or chips))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07
26	227	((29/33k,33m,563,564,564.1,564.2,564.7).CCLS.) or ((29/832,833,834,835,740,743).CCLS.) and (IC adj (chip or chips))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07
27	0	((29/33k,33m,563,564,564.1,564.2,564.7).CCLS.) or ((29/832,833,834,835,740,743).CCLS.) and (IC adj (chip or chips)) and cutters	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07
28	447	((29/33k,33m,563,564,564.1,564.2,564.7).CCLS.) or ((29/832,833,834,835,740,743).CCLS.) and board and electronic and horizontal	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:07
29	69	(29/\$).ccls. and electronic and board and cutters	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
30	361	((29/33k,33m,563,564,564.1,564.2,564.7).CCLS.) or ((29/832,833,834,835,740,743).CCLS.) and board and electronic and horizontal and vertical	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
31	6807	((29/33k,33m,563,564,564.1,564.2,564.7).CCLS.) or ((29/739,742,743,762,412,417,833).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
32	156	((29/33k,33m,563,564,564.1,564.2,564.7).CCLS.) or ((29/739,742,743,762,412,417,833).CCLS.) and cutters	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
33	323	(83/929.1,915.3,404.1).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
12	1	6205656.URPN.	USPAT	2004/02/21 16:08
13	1	6205656.URPN.	USPAT	2004/02/21 16:08
34	28	(((29/739,742,743,762,412,417,833).CCLS.) and convey\$5) and electronic\$3) and cut\$5) and fasten\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
35	118	((29/33k,33m,563,564,564.1,564.2,564.7).CCLS.) and convey\$5) and electronic	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
36	17	(((29/33k,33m,563,564,564.1,564.2,564.7).CCLS.) and convey\$5) and electronic) and (fasten\$4 or restrain\$4)) and cutter	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08

37	4	((((29/33k,33m,563,564,564.1,564,2,564.7).CCLS.) and convey\$5) and electronic) and chip) and IC	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
38	6	"6401317"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
39	23	((((29/33k,33m,563,564,564.1,564,2,564.7).CCLS.) and convey\$5) and electronic) and chip	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
40	15	("4558660" "5238876" "5273615" "5332406" "5370709" "5531857" "5534102" "5578133" "5622900" "5641714" "5733814" "5759874" "5863327" "5981361" "6259066").PN.	USPAT	2004/02/21 16:08
41	77	((29/564.1).CCLS.) and electronic\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
42	23	((((29/564.1).CCLS.) and electronic\$3) and (cutting or cutter or cut\$4)) and convey\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
43	4	("3849880" "3973996" "4149665" "4219926").PN.	USPAT	2004/02/21 16:08
44	6	"5801512"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
45	4	("3849880" "3973996" "4149665" "4219926").PN.	USPAT	2004/02/21 16:08
46	26	((29/840,832).CCLS.) and electronic and cut\$4) and manufacture near electronic	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
47	33	((29/840,832).CCLS.) and electronic and cutter\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
48	42	"3075630"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
49	1	cut near board near ic	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
50	1	H01L023/50.ipc. and (IC adj chip) near board and cutting	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
51	1	((IC adj chip) near board and cutting) and conveyor	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
52	2	(IC near board and cutting) and conveyor	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
53	15	(IC adj packages) and cutting and conveyor	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
54	1	4972572.URPN.	USPAT	2004/02/21 16:08

55	10	("0764851" "3469754" "3650232" "3722060" "3745808" "3866471" "4064917" "4099322" "4236301" "4619028").PN.	USPAT	2004/02/21 16:08
56	4	product adj accommodating adj device	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
57	61	((29/832,833,834,835,740,743).CCLS.) and electronic and cutting and convey\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
58	8	((29/832,833,834,835,740,743).CCLS.) and electronic and cutting and convey\$4 and cutters	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:08
59	113	((29/33k,33m,563,564,564.1,564.2,564.7).CCLS.) and cutters	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:09
60	35	((29/33k,33m,563,564,564.1,564.2,564.7).CCLS.) or ((29/832,833,834,835,740,743).CCLS.) and cutters and electronic	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:09
61	20	((29/\$).ccls. and electronic and board and cutters) and convey\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:09
62	16	(29/\$).ccls. and wiring adj board near cut\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:09
63	14	((29/33k,33m,563,564,564.1,564.2,564.7).CCLS.) or ((29/832,833,834,835,740,743).CCLS.) and board and electronic and cutters	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:09
64	2	wiring adj board near cut\$5 and cutters	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:09
65	35	board near cut\$5 and cutters and electronic	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:09
66	9	4846032.URPN.	USPAT	2004/02/21 16:09
67	26	((29/33k,33m,563,564,564.1,564.2,564.7).CCLS.) or ((29/739,742,743,762,412,417,833).CCLS.) and first near cutter	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:09
68	60	((29/33k,33m,563,564,564.1,564.2,564.7).CCLS.) or ((29/739,742,743,762,412,417,833).CCLS.) and cutters) and electronic\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:09
69	28	(((29/33k,33m,563,564,564.1,564.2,564.7).CCLS.) or ((29/739,742,743,762,412,417,833).CCLS.) and cutters) and electronic\$4) and convey\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:09
70	11	((83/929.1,915.3,404.1).CCLS.) and cutters	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:09
71	26	(83/915.3).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:09

72	80	(83/929.1).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:09
73	222	(83/404.1).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/02/21 16:09